



PK602 (v1.0) March 15, 2013

# 100% Material Declaration Data Sheet for Artix-7 FBG484 Package

**Average Weight: 2.1115 g**

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
<b>Silicon Die</b>					<b>0.237267</b>	<b>11.237</b>
	Silicon	7440-21-3	100.00		0.237267	
<b>Solder Bump</b>					<b>0.011261</b>	<b>0.533</b>
	Tin	7440-31-5	63.00		0.007094	
	Lead	7439-92-1	37.00		0.004167	
<b>Underfill</b>					<b>0.030000</b>	<b>1.421</b>
	Bisphenol F/ epichlorohydrin copolymer	9003-36-5	20.00		0.006000	
	Phenolic resin	Trade Secret	15.00		0.004500	
	Bisphenol A type liquid epoxy resin	25068-38-6	5.00		0.001500	
	Amine type accelerator	Trade Secret	5.00		0.001500	
	Silicon dioxide	60676-86-0	51.50		0.015450	
	Carbon black	1333-86-4	1.00		0.000300	
	Additives	Trade Secret	2.50		0.000750	
<b>Solder Ball</b>					<b>0.404317</b>	<b>19.148</b>
	Tin	7440-31-5	96.50		0.390166	
	Silver	7440-22-4	3.00		0.012130	
	Copper	7440-50-8	0.50		0.002022	
<b>Substrate</b>					<b>1.428702</b>	<b>67.661</b>
	Copper	7440-50-8	36.85		0.526477	
	Tin	7440-31-5	1.07		0.015287	
	Lead	7439-92-1	0.26		0.003715	
	Silver	7440-22-4	0.02		0.000286	
	BT Core	Trade Secret	48.20		0.688634	
	ABF	Trade Secret	11.12		0.158872	
	SolderMask	Trade Secret	2.48		0.035432	

© Copyright 2013 Xilinx, Inc. XILINX, the Xilinx logo, Virtex, Spartan, ISE, and other designated brands included herein are trademarks of Xilinx in the United States and other countries. All other trademarks are the property of their respective owners.

## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
03/15/2013	1.0	Xilinx Initial Release

---

## Notice of Disclaimer

Xilinx regards this materials data to be correct but makes no guarantee as to its accuracy or completeness, including, but not limited to, with respect to its compliance with applicable environmental laws and regulations. Xilinx subcontracts the production, test and assembly of hardware devices to independent third-party vendors and materials suppliers (“Contractors”). All data provided hereunder is based on information received from Contractors. Xilinx has not independently verified the accuracy or completeness of this information which is provided solely for your reference in connection with the use of Xilinx products.